LI0402E190R-10

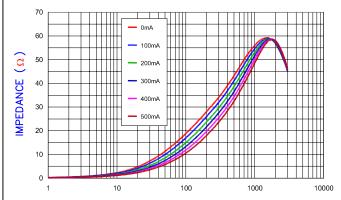
UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

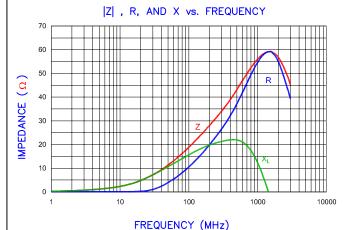
A 1.00 [.040] ± 0.15 [.006] B 0.50 [.020] ± 0.15 [.006] C 0.50 [.020] ± 0.15 [.006]

D 0.30 [.012] + MAX.

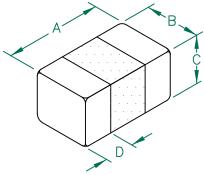
Z vs FREQUENCY IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)



AGILENT E4991A RF Impedance/Material Analyzer HP 16194A Test Fixture. TEST REF. 6231



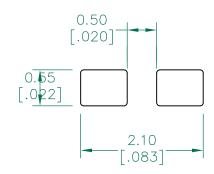


ELECTRICAL CHARACTERISTICS:									
Z @ 100M (<u>Ω</u>)	1Hz	DCR $\left(\begin{array}{c}\Omega\end{array}\right)$	Rated Current						
Nominal	19								
Minimum	14								
Maximum	24	0.10	500 mA						

NOTES: UNLESS OTHERWISE SPECIFIED

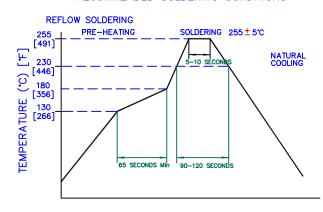
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 10,000 PCS/REEL, PAPER TAPE.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. OPERATING TEMP. RANGE: -40°C~+125°C. (INCLUDING SELF-HEATING)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension.)

RECOMMENDED SOLDERING CONDITIONS





	DIMENSIONS ARE IN mm [INCHE	This print is the property of Laird								
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				PROJECT/PART NUMBER:	REV	PART TY	PE:	DRAWN BY:		
С	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	LI0402E190R-10	С	co-	FIRE	JRK		
В	UPDATE COMPANY LOGO	07/09/08	JRK	DATE: 07/24/07 SCA	LE: NTS SHEET:		SHEET:	•		
Α	ORIGINAL DRAFT	07/24/07	JRK	lan a lan	OL #		2	of 2		
REV	DESCRIPTION	DATE	INT		•	-	_	· -		